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## **FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #20470**

Generic Copy

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**Issue Date:** 15-May-2014

**TITLE:** CS8182 Family Wafer Probe System Transfer

**PROPOSED FIRST SHIP DATE:** 15-Aug-2014 or sooner upon customer approval

**AFFECTED CHANGE CATEGORY(S):** Wafer Probe Equipment Change

**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**

Contact your local ON Semiconductor Sales Office or <bill.fontes@onsemi.com>

**SAMPLES:** Contact your local ON Semiconductor Sales Office

**ADDITIONAL RELIABILITY DATA:** Available

Contact your local ON Semiconductor Sales Office or < bill.fontes@onsemi.com>

**NOTIFICATION TYPE:**

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

**DESCRIPTION AND PURPOSE:**

Change the test system used for the wafer probe operation from Teradyne A360 to Eagle ETS500.

The purpose is to improve manufacturing efficiency by moving away from the obsolete Teradyne test system and using the more modern Eagle system.

**FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #20470****RELIABILITY DATA SUMMARY:****Reliability Test Results:**

<b>Test</b>	<b>Results</b>
Gauge R&R	passed
Test Correlation	passed
Cpk Check	passed
Over/Under Rejection Study	passed
Yield Analysis	passed
Spike Check	passed

**ELECTRICAL CHARACTERISTIC SUMMARY:**

No change to electrical characteristics.

**CHANGED PART IDENTIFICATION:**

No change to part visual appearance or identification.

**List of affected Parts:**

CS8182YDFR8G  
CS8183YDWF20G  
CS8183YDWFR20G  
CS8182DTRKG  
CS8182YDPSR5G  
SCV8182DSR4G